



Material Declaration Sheet

Vishay General Semiconductor - VGSC

Date 20/Aug/21

Part / Product Family Details

Vishay Part Number	RoHS Compliance Status	RoHS Compliance Date Code dd-mm-yyyy	Total product Weight (gm)	Resistance value	3rd Party Lab ICP Test Report Available	Manufacturing Location	Number of Exemption used
B230LA-(H)E3 to B240A-(H)E3 B330LA-(H)E3 to B360A-(H)E3 B120-E3 to B160-E3 BYS10-xx-E3 BYS11-90-E3 BYS12-90-E3 SS19-(H)E3 SL12-(H)E3 to SL13-(H)E3 SS1H9-(H)E3 to SS1H10-(H)E3 SS12-(H)E3 to SS16-(H)E3 SS22S-(H)E3 to SS24S-(H)E3 SS25S-(H)E3 to SS26S-(H)E3 SSA23L-(H)E3 to SSA24-(H)E3 SSA33L-(H)E3 to SSA34-(H)E3	YES WITH EXEMPTION	01-12-2004	0.064	N/A	Yes	China	One

Material Composition

Homogenous Material Name	Material Classification	Substance Name	CAS number	Weight of Substance (gm)	With respect to Homogenous Material		% with respect to Total Product Weight	RoHS Exemptions Used
					%	ppm		
Chip	Electronics (e.g. pc boards, displays)	Silicon and others (business secret)	-	0.00125	100.00	1000000	1.95	
Lead Frame	Copper (e.g. copper amounts in cable harnesses)	Copper	7440-50-8	0.02324	100.00	1000000	36.32	
Solder 92.5	Other special metals	Lead	7439-92-1	0.00236	92.50	925000	3.69	Exemption No:7(a)
		Tin	7440-31-5	0.00013	5.00	50000	0.20	
		Silver	7440-22-4	0.00006	2.50	25000	0.10	
		Quartz (SiO2)	14808-60-7	0.02472	70.00	700000	38.62	
Encapsulation	Other duromers	Epichlorohydrin,o-cresol,formalde polymer	29690-82-2	0.00565	16.00	160000	8.83	
		Phenol-formaldehyde resin	9003-35-4	0.00424	12.00	120000	6.62	
		Antimony oxide (Sb2-O3)	1309-64-4	0.00035	1.00	10000	0.55	
		Carbon-Black	1333-86-4	0.00009	0.25	2500	0.14	
		Additive & know-how	-	0.00026	0.75	7500	0.41	
Surface finish	Other special metals	Tin	7440-31-5	0.00163	100.00	1000000	2.55	

EU-RoHS Directive- MCV of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and MCV of **2015/863/EU** 0.01% by mass cadmium ,Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP)

Exemption Used 7(a) - Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Note :- (i) All information is based on data received from our vendors & subjected to change without prior notice.
(ii) Substance weight are derived from MSDS.

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